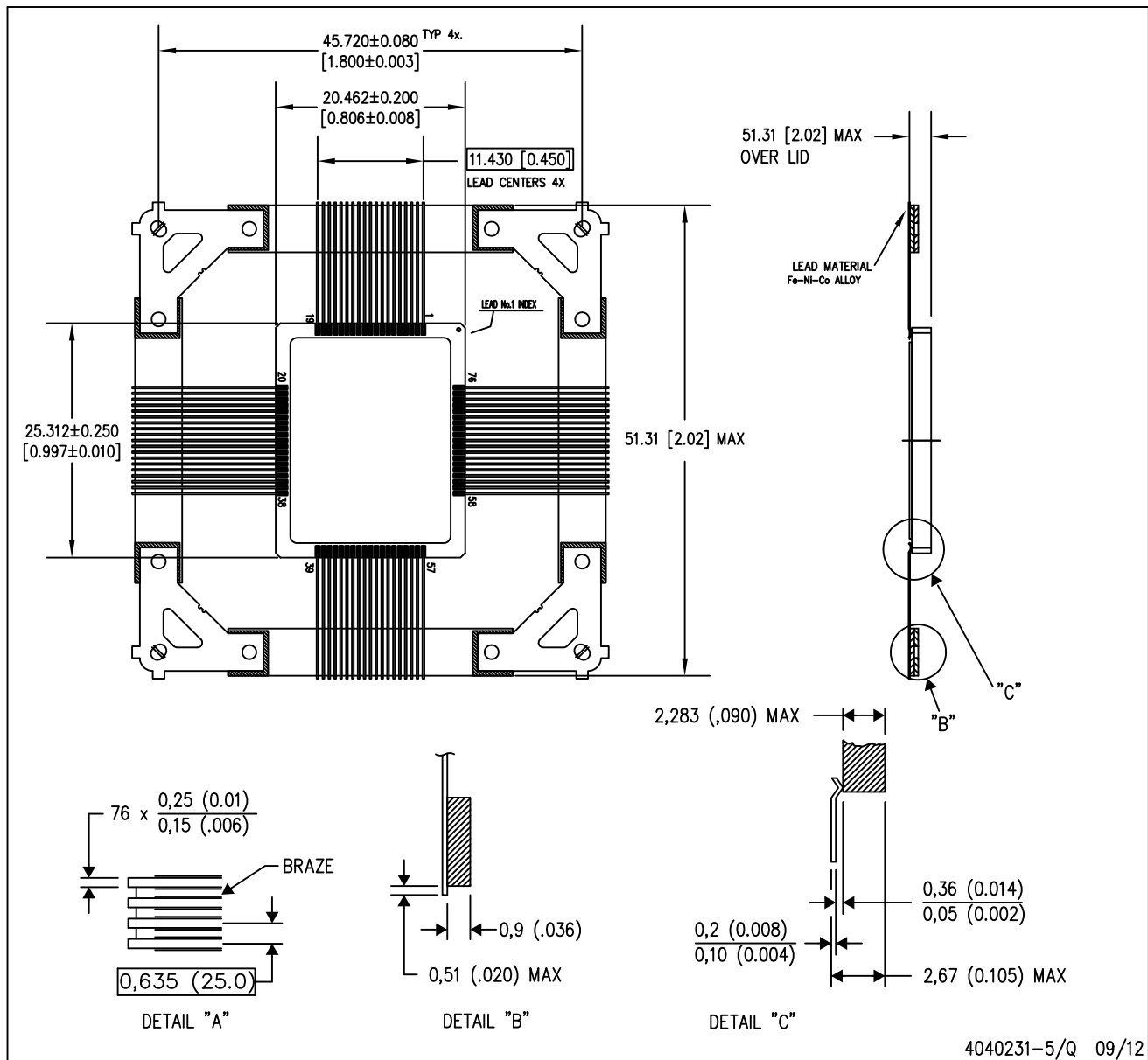


HFG (S-CQFP-F76)

CERAMIC QUAD FLATPACK WITH NCTB



- NOTES:
- A. All linear dimensions are in millimeters (inches).
 - B. This drawing is subject to change without notice.
 - C. Ceramic quad flatpack with flat leads brazed to non-conductive tie bar carrier.
 - D. This package is hermetically sealed with a metal lid.
 - E. The leads are gold plated and can be solderdipped.
 - F. Lid is connected to GND leads (see data sheet).

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